

Date: 01/29/21

Attendees:

Allan, Ravi, Anu, Bill, Ali, Shreyas, Suresh, Shahab, Liz, Phillippe, DJ, Quinn, Paul, David Ra, David Re, David A, Mudasir, Gus, Scott, Reza, Javi, JP, Andreas, Bapi, Rob, Sam, Lei, Swami, Weifeng

<https://global.gotomeeting.com/join/950275429>

1. Rolling Agenda:
 - a. January 29th - Architecture revisited
 - b. Feb 5th - OAM Tool deep dive
 - i. Get idea on the libraries and common features
 - c. CPO discussion sometime
 - d. Biz workshop - Ravi
 - e. DiPort, Gary Miller
 - f. Ultra-short reach optical (DJ) - Avcena
 - g. Debendra@Intel + others
2. Agenda
 - a. Does everyone on the call know how to access these weekly minutes - groups.io
 - b. BoW test chip CFP in flight
 - c. Bill Chen - Annual Heterogeneous Integration Roadmap meeting 2/24-2/26.
Everyone is invited
 - d. MEPTEC workshop on Too Hot to Test 2/9-2/11.
3. Ali/Anu Platform Discussion
 - a. Aiming for a consensus view of a platform, subsystem - creating a white paper
 - b. Thoughts on modularization
 - i. Good positive reception
 - ii. Discussion notes from Ali
 - iii. DJ - can we reuse existing form factors since OAM and OCP NIC 3.0 are form factors with a big ecosystem
 - iv. Allan - a lot of the OAM signal budget disappears into the module. OAM modules are large. Make the module itself the substrate?
 - v.
4. Weekly workstream minutes
 - a. BoW - <https://github.com/opencomputeproject/ODSA-BoW/issues/38>:
 - i. BoW spec 1.0 - good progress
 - b. CDX -
https://docs.google.com/document/d/1ZVA1_qMWSdIhjHBF21pwucmy9LqAID8fQwpog8Vcxl/edit?usp=sharing
 - c. Link Layer -
https://docs.google.com/document/d/1v1bfsgkG4ef8Sqs1IBb1_tvIjl-ffJS0T8-PnESxTk/edit?usp=sharing

- i.
- d. PIPE -
 - https://docs.google.com/document/d/1g9m6FdBaWzHj8BIRI5ADlbJVT-GR_8ODVaxHTg5Snw0/edit?usp=sharing
 - i. Aiming for final clean up. Going to publish as a white paper
- e. PoC HW
 - <https://docs.google.com/document/d/1UOdbOrF2TG7zZQCadLFZ1ujljAkl3FXra5wGJ-QkZ1o/edit?usp=sharing>
 - i. Board bring up in progress
- f. PoC SW -
 - <https://docs.google.com/document/d/1kpgZL1mH-sMOdA0wWFOcnNLactSZdo68jw-UEVcqLZo/edit?usp=sharing>
 - i. Working on remote access
- g. Open HBI - contact Kenneth Ma
- h. Business workflow
 - i.
- 5. Speaker ideas
 - a. HBM Thermal Management
 - b. CEA-LETI
 - c. Quality and Reliability - ESD, aging, electromigration - Bill HIR workgroup, ANSYS, packaging reliability - thermal effects, mechanical - as applies to chiplets
 - d. Anyone making chiplets - commercial talks focused on chiplets
 - e. Memory access discussion - HBM, GenZ, OMI - how do they become compatible with chiplets - WD/Micron/IBM/Samsung/SK/Seagate - new protocol? Sequence of memory-focused talks - Allan - October
 - f. Prof. Flynn from Michigan
 - g. DARPA official CHIPS - Eelco - October/November
 - h. CHIPS - Andreas - October
 - i. TSMC - Bill, Suresh
 - j. Transaction Protocol for D2D review
 - k. Bit errors in substrates
 - l. End user workgroup - DJ
 - m. Any other foundry (Global) or AMAT?
 - n. Ken, Open HBI in February
 - o. Quinn in February - Software
 - p. Someone @ ARM in Q1
 - q. Bill@IEEE in March for the HIR
 - r. Allan - Modular design for mini OAM, bare die on the module
 - s. Sam will come up with something
 - t. Ali - top-level architecture - modular design
 - u. Philippe@Boyd - thermal management
 - v. Nhat@Rambus - check on internal talks, cover the ISSCC talk
 - w. Shahab@ISSCC talks - chase them down

- x. Ravi - disaggregation of SRAM, persistent memory,
- y. DJ@End User in Feb
- z. Jawad - How do we use existing chips as chiplets - panel. How do we define a chiplet, isn't this MCM packaging? What's different? What is the current MCM biz model, state of flow. How do understand the die sales model and its relevance for chiplets. Can we use the PoC as a starting point + Ali
- aa. Ali@Mature process nodes
- bb. Get panelists to do longer talks.
- cc. OAM expert to do a talk